



# STB70NF02L

## N-CHANNEL 20V - 0.006 Ω - 70A D<sup>2</sup>PAK LOW GATE CHARGE STriпFET™ POWER MOSFET

PRELIMINARY DATA

TYPE	V <sub>DSS</sub>	R <sub>D(on)</sub>	I <sub>D</sub>
STB70NF02L	20 V	<0.009 Ω	70 A

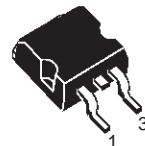
- TYPICAL R<sub>D(on)</sub> = 0.016 Ω
- TYPICAL Q<sub>G</sub> = 36 nC @ 10V
- OPTIMAL R<sub>D(on)</sub> x Q<sub>G</sub> TRADE-OFF
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED

### DESCRIPTION

This application specific Power Mosfet is the third generation of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

### APPLICATIONS

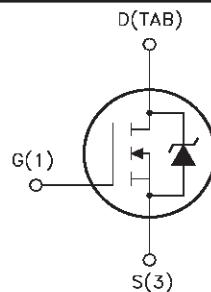
- SPECIFICALLY DESIGNED AND OPTIMISED FOR HIGH EFFICIENCY CPU CORE DC/DC CONVERTERS



D<sup>2</sup>PAK  
TO-263  
(suffix "T4")

ADD SUFFIX "T4" FOR ORDERING IN TAPE & REEL

### INTERNAL SCHEMATIC DIAGRAM



SC07580

### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	20	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	20	V
V <sub>GS</sub>	Gate- source Voltage	±20	V
I <sub>D</sub>	Drain Current (continuos) at T <sub>C</sub> = 25°C	70	A
I <sub>D</sub>	Drain Current (continuos) at T <sub>C</sub> = 100°C	50	A
I <sub>DM(•)</sub>	Drain Current (pulsed)	280	A
P <sub>tot</sub>	Total Dissipation at T <sub>C</sub> = 25°C	100	W
	Derating Factor	0.67	W/°C
T <sub>stg</sub>	Storage Temperature	-65 to 175	°C
T <sub>j</sub>	Max. Operating Junction Temperature	175	°C

(•)Pulse width limited by safe operating area

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### THERMAL DATA

$R_{thj-case}$	Thermal Resistance Junction-case Max	Max	1.5	°C/W
$R_{thj-amb}$	Thermal Resistance Junction-ambient Max	Max	62.5	°C/W
$T_j$	Maximum Lead Temperature For Soldering Purpose		300	°C

### ELECTRICAL CHARACTERISTICS ( $T_{case} = 25^\circ\text{C}$ unless otherwise specified)

#### OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250 \mu\text{A}$ $V_{GS} = 0$	20			V
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating}, T_C = 125^\circ\text{C}$			1 10	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate-body Leakage Current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA

#### ON (\*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250 \mu\text{A}$	1			V
$R_{DS(\text{on})}$	Static Drain-source On Resistance	$V_{GS} = 10 \text{ V}$ $I_D = 35 \text{ A}$ $V_{GS} = 5 \text{ V}$ $I_D = 18 \text{ A}$		0.006 0.011	0.009 0.015	$\Omega$ $\Omega$
$I_{D(\text{on})}$	On State Drain Current	$V_{DS} > I_{D(\text{on})} \times R_{DS(\text{on})\text{max}}$ $V_{GS} = 10\text{V}$	70			A

#### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(*)}$	Forward Transconductance	$V_{DS} > I_{D(\text{on})} \times R_{DS(\text{on})\text{max}}$ $I_D=35 \text{ A}$		40		S
$C_{iss}$ $C_{oss}$ $C_{rss}$	Input Capacitance Output Capacitance Reverse Transfer Capacitances	$V_{DS} = 25\text{V}$ $f = 1 \text{ MHz}$ $V_{GS} = 0$		1500 900 200		pF pF pF

**ELECTRICAL CHARACTERISTICS** (continued)**SWITCHING ON**

<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$t_{d(on)}$ $t_r$	Turn-on Delay Time Rise Time	$V_{DD} = 10 \text{ V}$ $I_D = 35 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 4.5 \text{ V}$ (see test circuit, Figure 3)		480		ns ns
$Q_g$ $Q_{gs}$ $Q_{gd}$	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 16 \text{ V}$ $I_D = 46 \text{ A}$ $V_{GS} = 10 \text{ V}$		36 5 10	45	nC nC nC

**SWITCHING OFF**

<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$t_{d(off)}$ $t_f$	Turn-off Delay Time Fall Time	$V_{DD} = 10 \text{ V}$ $I_D = 35 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 4.5 \text{ V}$ (Resistive Load, see fig.3)		30 110		ns ns

**SOURCE DRAIN DIODE**

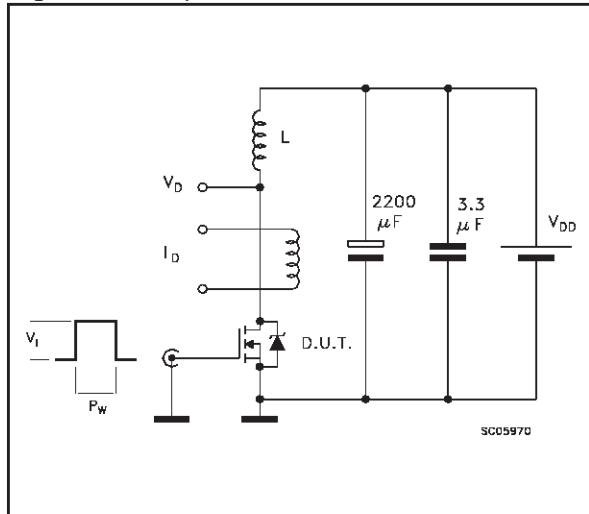
<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$I_{SD}$ $I_{SDM(\bullet)}$	Source-drain Current Source-drain Current (pulsed)				70 280	A A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 70 \text{ A}$ $V_{GS} = 0$			1.2	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 70 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 15 \text{ V}$ $T_j = 150 \text{ }^\circ\text{C}$ (see test circuit, Figure 5)		60 100 2		ns nC A

(\*)Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.

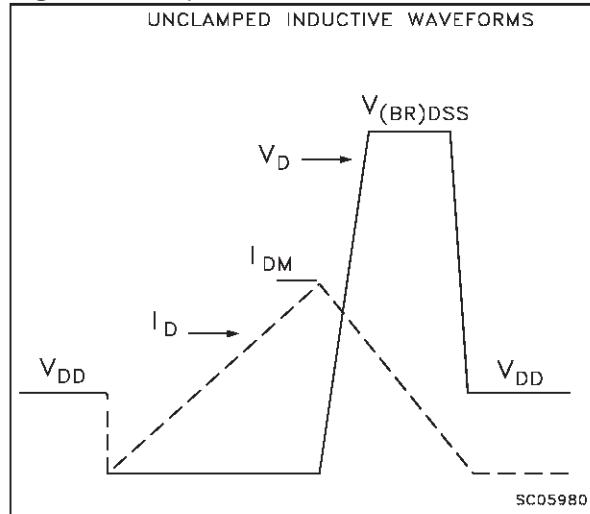
(\bullet)Pulse width limited by safe operating area.

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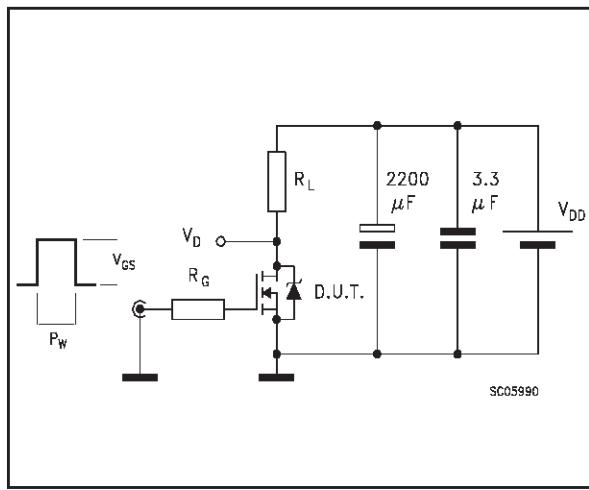
**Fig. 1: Unclamped Inductive Load Test Circuit**



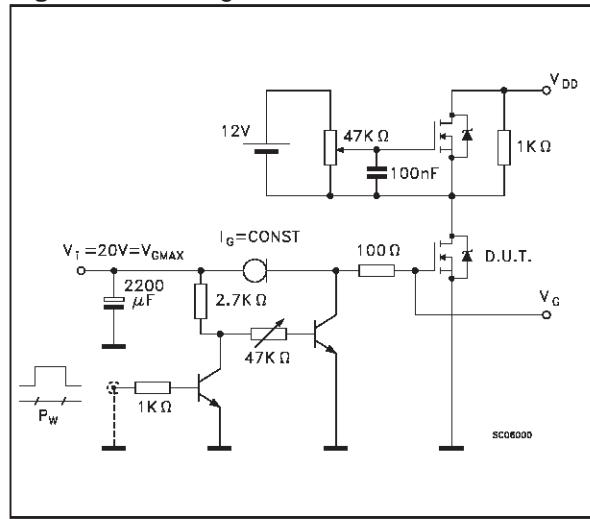
**Fig. 2: Unclamped Inductive Waveform**



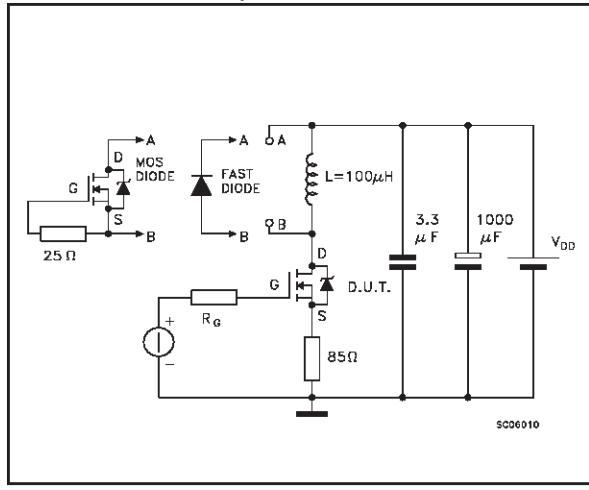
**Fig. 3: Switching Times Test Circuits For Resistive Load**



**Fig. 4: Gate Charge test Circuit**

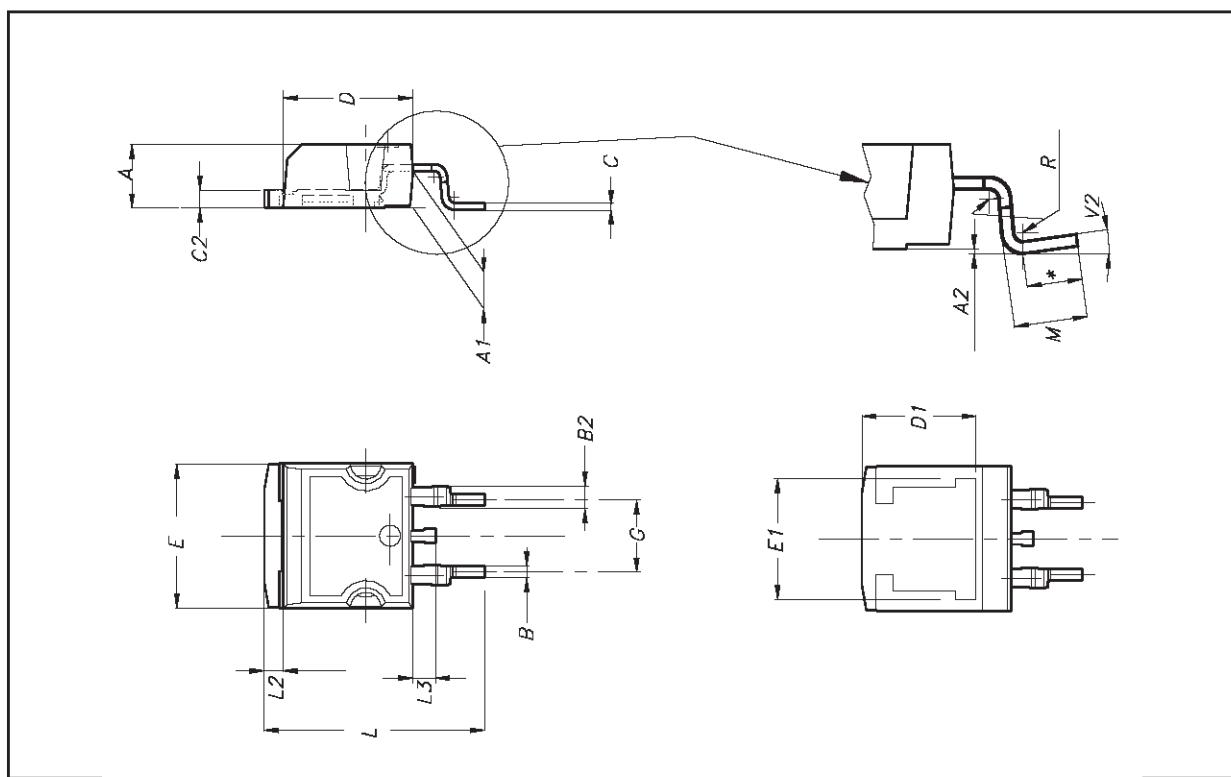


**Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times**



D<sup>2</sup>PAK MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0°		8°			



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